

Amendments to the Claims:

Claims 1-5 (Cancelled)

6. (New) An electronic component comprising:
an insulative chip cover having a housing section in a lower surface thereof, and having a bonding surface on said lower surface;
a flip chip including a base and a plurality of electrodes on an electrode surface of said base, said chip being accommodated in said housing portion of said chip cover;
an anisotropic conductive adhesive agent applied to said electrodes of said chip;
an insulative adhesive agent applied to said bonding surface of said chip cover, said insulative adhesive agent having the same curing condition as said anisotropic conductive adhesive agent, each of said anisotropic conductive adhesive agent and said insulative adhesive agent being press-heated for a predetermined length of time so as to be in a temporarily cured state.
7. (New) The electronic component of claim 6, wherein said chip has a bonding surface on a periphery of said electrode surface, said insulative adhesive agent being applied to said bonding surface of said electrode surface.
8. (New) The electronic component of claim 6, wherein said anisotropic conductive adhesive agent is screen-printed onto said electrodes, and said insulative adhesive agent is screen-printed onto said bonding surface.
9. (New) The electronic component of claim 6, wherein said chip cover has a radiating portion.

10. (New) The electronic component of claim 9, wherein said radiating portion comprises an opening on at least one end surface of said chip cover so as to communicate with an exterior of said chip cover.

11. (New) The electronic component of claim 6, wherein each of said anisotropic conductive adhesive agent and said insulative adhesive agent is responsive to a predetermined heating temperature so as to be changed from said temporarily cured state to a cured state.

12. (New) The electronic component of claim 6, wherein no insulative adhesive agent is applied to said electrodes.

13. (New) A method of mounting an electronic component, comprising:
accommodating a flip chip in a housing portion in a lower surface of an insulative chip cover, the flip chip having a semiconductor element with a plurality of electrodes arranged in a planar manner, the chip cover having a bonding surface on the lower surface thereof;

applying an anisotropic conductive adhesive agent to the electrodes;

applying an insulative adhesive agent to the bonding surface of the chip cover, the insulative adhesive agent having the same curing condition as the anisotropic conductive adhesive agent;

heat-pressing the anisotropic conductive adhesive agent and the insulative adhesive agent so as to temporarily cure the anisotropic conductive adhesive agent and the insulative adhesive agent to thereby form a mountable electronic component;

positioning the mountable electronic component on a circuit board having substrate electrodes so that the electrodes of the flip chip are aligned with the substrate electrodes;

mounting a crimping tool on the chip cover; and

pressing the crimping tool against the chip cover while heating the mountable electronic component so as to hot-melt the anisotropic conductive adhesive agent and the insulative

adhesive agent and so as to press the mountable electronic component against the circuit board to thereby electrically connect the electrodes of the flip chip to the substrate electrodes.

14. (New) The method of claim 13, wherein said applying of the anisotropic conductive adhesive agent to the electrodes comprises screen-printing the anisotropic conductive adhesive agent onto the electrodes, and said applying of the insulative adhesive agent to the bonding surface of the chip cover comprises screen-printing of the insulative adhesive agent onto the bonding surface of the chip cover.

15. (New) The method of claim 13, wherein the chip cover has a radiating portion.

16. (New) The method of claim 13, wherein said applying of the insulative adhesive agent includes applying no insulative adhesive agent to the electrodes.

17. (New) An electronic component to be mounted on a circuit board, said electronic component comprising:

- an insulative base having a mounting surface;
- an electrode portion on said mounting surface, said electrode portion including at least one electrode;
- a space portion on said mounting surface, said space portion have no electrodes;
- an anisotropic conductive adhesive agent applied to said electrode portion; and
- an insulative adhesive agent applied to said space portion, said insulative adhesive agent having the same curing condition as said anisotropic conductive adhesive agent, each of said anisotropic conductive adhesive agent and said insulative adhesive agent being in a temporarily cured state.

18. (New) The electronic component of claim 17, wherein said electrode portion is located at a center of said mounting surface of said insulative base, and said space portion is located around said electrode portion.

19. (New) The electronic component of claim 17, wherein said space portion is located at a center of said mounting surface of said insulative base, and said electrode portion is located around said space portion.

20. (New) The electronic component of claim 17, wherein said electrode portion includes a plurality of electrodes spaced apart at predetermined intervals.

21. (New) The electronic component of claim 17, wherein the circuit board has at least one projecting electrode corresponding to said at least one electrode of said electrode portion.

22. (New) The electronic component of claim 17, wherein no insulative adhesive agent is applied to said at least one electrode of said electrode portion.